

# INTERNATIONAL STANDARD

**Process management for avionics – Atmospheric radiation effects –  
Part 1: Accommodation of atmospheric radiation effects via single event effects  
within avionics electronic equipment**



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INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

PRICE CODE **XD**

ICS 03.100.50; 31.020; 49.060

ISBN 978-2-83220-099-5

**Warning! Make sure that you obtained this publication from an authorized distributor.**

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PROCESS MANAGEMENT FOR AVIONICS –  
ATMOSPHERIC RADIATION EFFECTS –****Part 1: Accommodation of atmospheric radiation effects via  
single event effects within avionics electronic equipment**

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IEC 62396-1 has been prepared by IEC technical committee 107: Process management for avionics.

IEC 62396-1 cancels and replaces IEC/TS 62396-1 published in 2006.

This International Standard includes the following technical changes with respect to the Technical Specification:

- a) Guidance has been provided on the environment for altitudes above 60 000 feet (18,3 km) and the effects on electronics are documented in Annex E and F;
- b) Annex G has been added to provide late news as of 2011 on SEE cross-sections applicable to the atmospheric neutron environment.

The text of this international standard is based on the following documents:

FDIS	Report on voting
107/176/FDIS	107/182/RVD

Full information on the voting for the approval of this international standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 62396 series, published under the general title *Process management for avionics – Atmospheric radiation effects*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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